

ABSTRACT

To provide a film capable of suppressing both of formation of wrinkles when a release film is suction-attached to a cavity surface in compression molding, and formation of wrinkles when the cavity bottom surface to which the release film has been suction-attached is raised; and a method for producing a semiconductor element by using said film. A laminated film 1 comprises a layer 3 of shrinkable film, of which the storage elastic modulus E' at 180°C is at least 70 MPa, and the thermal shrinkage in 30 minutes at 180°C, with reference to 20°C, in each of the machine direction (MD) and the transverse direction (TD), is at least 3%, and a fluororesin layer 5 present on one side or both sides of the shrinkable film layer 3.